



2021 IEEE MTT-S  
International Microwave Workshop Series  
On Advanced Materials and Processes  
for RF and THz Applications (IMWS-AMP 2021)

Nov 15-17, 2021, Chongqing, China

[www.nusri.cn/imws-amp2021](http://www.nusri.cn/imws-amp2021)

Call for Papers



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email: [imws2021@nusri.cn](mailto:imws2021@nusri.cn)

IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications (IMWS-AMP 2021) is co-organized by National University of Singapore (NUS) Chongqing Research Institute, Chongqing University, University of Electronic Science and Technology of China, NUS Suzhou Research Institute, Northwestern Polytechnical University, Science and Technology on Monolithic Integrated Circuits and Modules Laboratory, and IEEE AP/MTT Joint Societies Chongqing Chapter. IMWS-AMP 2021 is a continuation of a series of annual international events held in Suzhou, China (2015), Chengdu, China (2016), Pavia, Italy (2017), Michigan, USA (2018), Bochum, Germany (2019) and Virtual (2020). The purpose of this platform is to boost technical and educational activities as well as exchanges and collaborations within the international microwave community.

IMWS-AMP2021 will be held in Chongqing, China on **Nov 15-17, 2021**. IMWS-AMP2021 will feature both invited and contributed papers. Distinguished researchers will be invited to deliver keynote speeches on technology trends and significant advances in relevant topics. Contributed papers are solicited for the same topics as listed below.

### Topics

The topics include, but are not limited to, the following technical areas:

- Carbon nanotubes and 2D electronic and optoelectronic devices (e.g. graphene and beyond graphene)
- Wide bandgap and other emerging semiconductor materials (e.g. ionic materials) based electronic devices: characterization, modelling and design
- Advanced silicon, integrated passive devices and through substrate via
- Low-temperature co-fired ceramic and liquid crystal polymer based microwave devices
- Large-area printing, inkjet printing and 3D printing materials and processes for RF and THz applications
- Fan-out wafer/panel level packaging for 5G mmWave and IoT, etc.
- Flexible materials for RF electronics and antennas
- Engineered metamaterials and plasmonics for absorption, cloaking, and wave manipulation
- Ferromagnetic materials and superconducting materials
- Spin-wave and magnetic crystal materials
- Passive/active microwave and terahertz devices (material characterization, fabrications, and applications)
- Antennas with advanced/complex/artificial materials and processes

### Electronic Paper Submission:

Prospective authors are invited to submit manuscripts in electronic (PDF) format only. All papers must be written in English and limited to three pages including text, references, and figures. A template is available on the IMWS-AMP2021 website. Papers submitted will be peer reviewed and all papers presented at the conference will be included in IEEE Xplore pending quality review. Note that one-page abstracts can also be acceptable, but it will not be included in IEEE Xplore.

### Special Issues in IEEE Transactions on Microwave Theory and Techniques and IEEE Journal of Electromagnetics, RF and Microwaves in Medicine and Biology:

Authors of all papers presented at IEEE IMWS-AMP 2021 are invited to submit an expanded version of their papers to a Mini-Special Issue of (1) IEEE Transactions on Microwave Theory and Techniques, or (2) IEEE Journal of Electromagnetics, RF and Microwaves in Medicine and Biology. Every paper will be reviewed by the respective journal in the same manner as all other regular submissions.

### Best Student Paper Awards:

Awards for Best Student Papers will be presented to the winners at the conference. The Awards Committee will judge the papers primarily on originality, significance, technical soundness, presentation, and reviewers' reports. To qualify for the Best Student Paper, the author must be a full-time student who presents, as the first author, the paper at the conference.

### Important Dates:

Paper Submission Deadline:	July 15, 2021	Aug 15, 2021
Notification of Acceptance:	Aug 31, 2021	Sept 15, 2021
Final paper Submission:	Sept 15, 2021	Sept 30, 2021

### Exhibitions:

Exhibition of company products is solicited for the areas related to the topics. Interested parties should contact the Conference Secretariat.

